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Journal Information

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Classification History

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2026			✓	
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2023			✓	
2021/2022			✓	
2020			✓	
2019			✓	
2018				

Classification: The table above shows all journal classifications recorded for each classification year in the Green Journals database. A journal may have more than one classification in the same year.

Recent Articles

Evaluating MEMS Switch Lifetime at Cryogenic Temperatures
2026-9-15 Vol. 23 Issue 3
Authors: Elizabeth Sorenson, Peter Bradley, Damian Lauria et al.
DOI: 10.4071/001c.163972

Glass Packaging for Chiplets Heterogeneous Integration
2026-9-15 Vol. 23 Issue 3
Authors: John H Lau
DOI: 10.4071/001c.169986

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2026-9-15 Vol. 23 Issue 3
Authors: John H Lau
DOI: 10.4071/001c.164804

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2026-6-15 Vol. 23 Issue 2
Authors: Linus Daniel Stier, Marc Dreissigacker, Mathias Koch et al.
DOI: 10.4071/001c.161566

Laser Cleaning Cylindrical Cells for Optimum Wire Bondability
2026-6-15 Vol. 23 Issue 2
Authors: Dominik Haering, Mike McKeown, Louis Castellanos et al.
DOI: 10.4071/001c.161569

Scalable Manufacturing of Multi-Stacked Copper Spiral Inductors Using a Novel Fully Additive Method
2026-3-15 Vol. 23 Issue 1
Authors: Roghayeh Imani, Shailesh Chouhan, Jerker Delsing
DOI: 10.4071/001c.156232

Advanced Modeling of Cure Shrinkage and Viscoelasticity for Warpage Prediction on Image Sensor Packaging
2026-3-15 Vol. 23 Issue 1
Authors: Ning Liu, Shahram Seyedmohammadi, Howard Yun et al.
DOI: 10.4071/001c.156183

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2026-3-15 Vol. 23 Issue 1
Authors: Kevin Antony Jesu Durai, Duwage Anushka Sandaruwan Perera, Khanh Tuyet Anh Tran et al.
DOI: 10.4071/001c.157833

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2026-3-15 Vol. 23 Issue 1
Authors: Shyam Muralidharan Nair, Duwage Anushka Sandaruwan Perera, Gavin Farmer et al.
DOI: 10.4071/001c.156190

Jet Dispensing of Liquid Metal as a Thermal Interface Material
2025-12-15 Vol. 22 Issue 4
Authors: Sunny Agarwal, Miloš Lazić
DOI: 10.4071/001c.147767